

PROXIMITY HEAD HEATING METHOD AND APPARATUS

ABSTRACT

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Provided is an apparatus and a method for heating fluid in a proximity head.

A fluid source supplies fluid to a channel within the proximity head. The fluid flows in the channel, through the proximity head, to an outlet port located on a bottom surface of the proximity head. Further, within the proximity head is a heating portion
10 that heats the fluid. Various methods can heat the fluid in the heating portion. For example, the fluid can be heated via resistive heating and heat exchange. However, any mechanism for heating fluid in the proximity head is possible. After heating the fluid, the proximity head delivers the heated fluid through the outlet port to a surface of a semiconductor wafer. An inlet port proximately disposed near the outlet port
15 vacuums the heated fluid to remove the heated fluid from the surface of the semiconductor wafer.

(Fig, 1A)